

2024 The 9th International Conference on Integrated Circuits and Microsystems

October 25-27, 2024 | Wuhan, China

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9th ICICM2024

2024 The 9th International Conference on Integrated Circuits and Microsystems (ICICM 2024) will be held in Wuhan, China on October 25-27, 2024, which is co-sponsored by Southeast University, China; University of Electronic Science and Technology of China, and Wuhan University of Technology, China.

Invited Speakers Recruitment

- ICICM 2024 recruit domestic and international invited speakers in the Integrated Circuits and Microsystems field.
- ICICM 2024 will assign the selected presentations to relevant forums. Applicants are requested to send their resumes, academic achievements, speech title and abstract, and two-inch photo as attachments to icicm_conf@vip.163.com.
- Invited speakers are required to share best practices and research results, and are not allowed to promote any products or services during the speech.

Topics

Include but not limited

- Progress of EDA algorithms
- EDA in High Performance Computing (HPC)
- EDA in analog and mixed-signal design
- EDA for FPGA and ASIC design
- IC computer-aided design technology, DFM
- Low power, RF devices and circuits
- Silicon/Germanium Devices and Device Physics
- Compound semiconductor devices and circuits
- 3D integration and advanced packaging
- Packaging and testing technology, equipment technology
- Displays, sensors and MEMS
- Energy harvesting and wireless sensors
- AI digital and analog software and hardware optimization
- Communications ASICs and systems
- Batteries and energy storage systems

For more topics, please visit at: <http://icicm.net/call-for-papers.html>

Track Recruitment

If you are willing to organise one or more tracks, please contact us to get more details. All papers in track will also be included in the conference proceedings and indexed by EI Compendex and Scopus.

Submission

- Full paper (Presentation & Publication)
- Abstract (Presentation only)

Submission Link:

<https://easychair.org/conferences/?conf=icicm2024>

Email submission: icicm_conf@vip.163.com

Full paper template (Word): <http://icicm.net/files/Template.doc>

Full paper template (Latex):

<http://icicm.net/files/IEEE-conference-proceeding-Latex.rar>

Publication

Submitted papers will be Peer-Reviewed (Double Blind) and the accepted ones will be collected in the conference proceedings and indexed by EI Compendex and Scopus, etc.

**Proceedings of ICICM2016-2023 have been successfully include in IEEE Xplore and indexed by EI Compendex and Scopus already!

Conference History

ICICM2016	Chengdu	IEEE	ISBN: 978-1-5090-2814-6
ICICM2017	Nanjing	IEEE	ISBN: 978-1-5386-3506-3
ICICM2018	Shanghai	IEEE	ISBN: 978-1-5386-8311-8
ICICM2019	Beijing	IEEE	ISBN: 978-1-7281-5132-8
ICICM2020	Nanjing	IEEE	ISBN: 978-1-7281-8978-9
ICICM2021	Nanjing	IEEE	ISBN: 978-1-6654-5886-3
ICICM2022	Xi'an	IEEE	ISBN: 978-1-6654-6042-2
ICICM2023	Nanjing	IEEE	ISBN: 979-8-3503-1849-4

Important Dates

Submission Deadline	Camera Ready	Listener Registration
September 20, 2024	October 15, 2024	October 20 2024

Organizing Committee

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